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## **FCH041N60F**

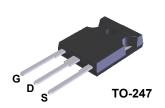
# N-Channel SuperFET<sup>®</sup> II FRFET<sup>®</sup> MOSFET 600 V, 76 A, 41 m $\Omega$

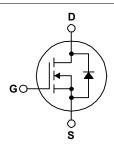
#### **Features**

- 650 V @ T<sub>J</sub> = 150°C
- Typ.  $R_{DS(on)}$  = 36 m $\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>q</sub> = 277 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 748 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

#### **Description**

SuperFET® II MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FCH041N60F	Unit
V <sub>DSS</sub>	Drain to Source Voltage			600	V
\ /	Cata ta Cauraa Valtaria	- DC		±20	V
$V_{GSS}$	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V
1	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		76	^
ID	Drain Current	- Continuous (T <sub>C</sub> = 100°C)		48.1	A
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	228	Α
E <sub>AS</sub>	Single Pulsed Avalanche Ene	ergy	(Note 2)	2025	mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	15	Α
E <sub>AR</sub>	Repetitive Avalanche Energy		(Note 1)	5.95	mJ
مار . الما	MOSFET dv/dt		100	\ //	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	50	V/ns
D	Device Discipation	(T <sub>C</sub> = 25°C)		595	W
$P_{D}$	Power Dissipation - Derate Above 25°C		4.76	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temp	erature Range		-55 to +150	οС
T <sub>L</sub>	Maximum Lead Temperature	for Soldering, 1/8" from Case for 5 S	Seconds	300	οС

#### **Thermal Characteristics**

Symbol	Parameter	FCH041N60F	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.21	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	*C/VV

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH041N60F	FCH041N60F	TO-247	Tube	N/A	N/A	30 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Breakdown Voltage	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}, T_J = 25^{\circ}\text{C}$	600	-	-	V
BV <sub>DSS</sub>		$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}, T_J = 150^{\circ}\text{C}$	650	-	-	V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	0.67	-	V/°C
I	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	-	10	
IDSS		$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	267	-	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3	-	5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 38 \text{ A}$	-	36	41	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 38 A	-	64.5	-	S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	.,	-	10800	14365	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1  MHz	-	324	430	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	-	4.5	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	185	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	748	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 38 A,	-	277	360	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	65.3	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	116	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.0	-	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	63	136	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 380 \text{ V}, I_D = 38 \text{ A},$	-	66	142	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{G} = 4.7 \Omega$	-	244	498	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	53	116	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	77	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	231	Α
$V_{SD}$	Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A		-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A,	-	214	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	1.79	-	μС

#### Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2.  $I_{AS}$  = 15 A,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.
- 3.  $I_{SD} \le 38$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le 380$  V, starting  $T_J$  = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

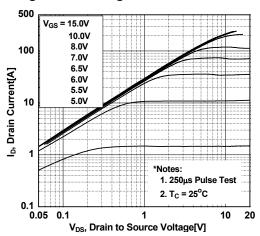


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

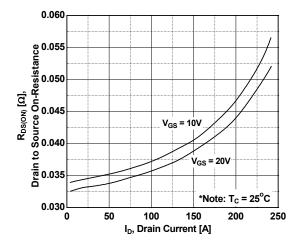


Figure 5. Capacitance Characteristics

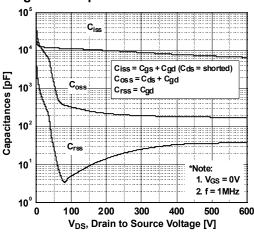


Figure 2. Transfer Characteristics

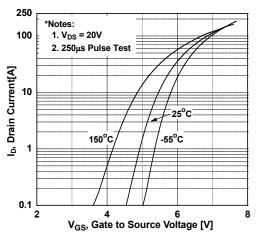


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

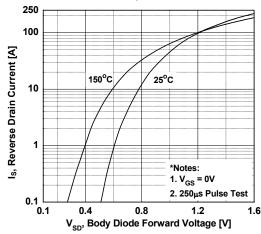
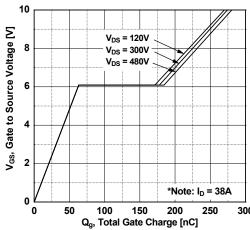


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

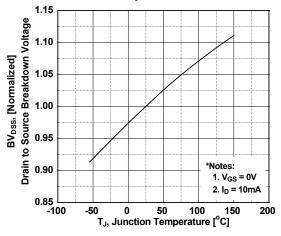


Figure 9. Maximum Safe Operating Area

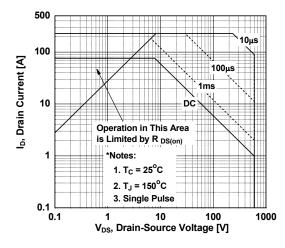


Figure 11. Eoss vs. Drain to Source Voltage

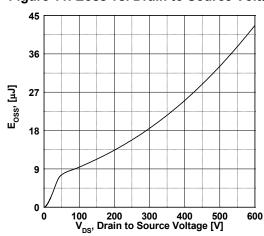


Figure 8. On-Resistance Variation vs. Temperature

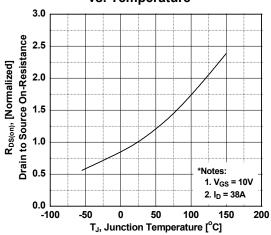
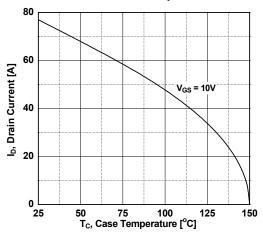
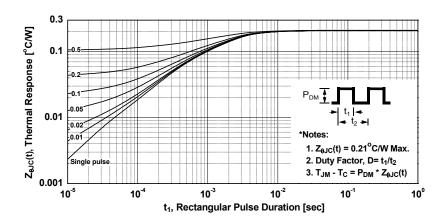


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics** (Continued)

Figure 12. Transient Thermal Response Curve



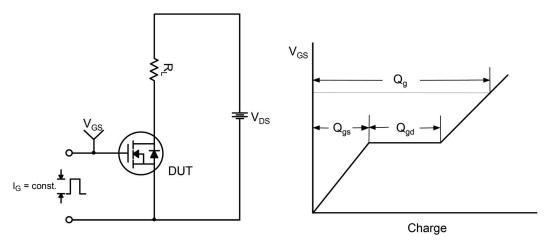


Figure 13. Gate Charge Test Circuit & Waveform

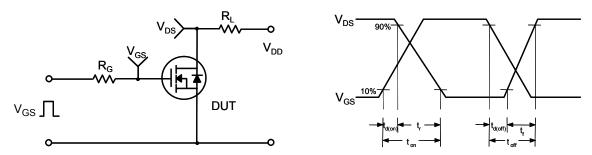


Figure 14. Resistive Switching Test Circuit & Waveforms

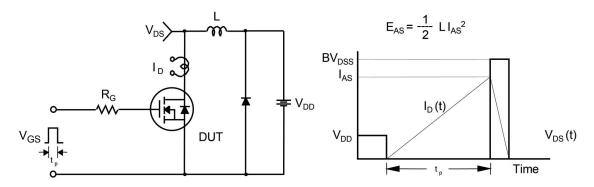
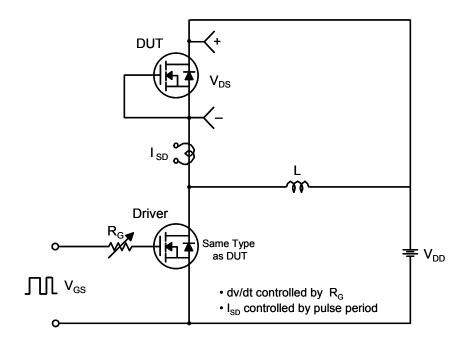


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



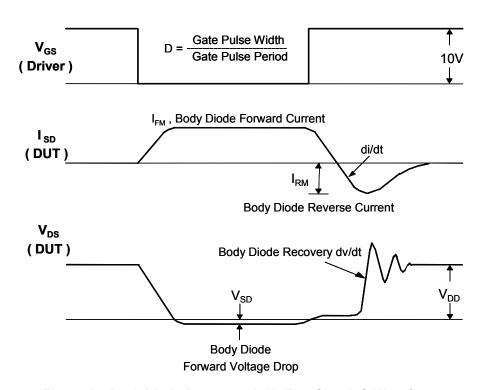
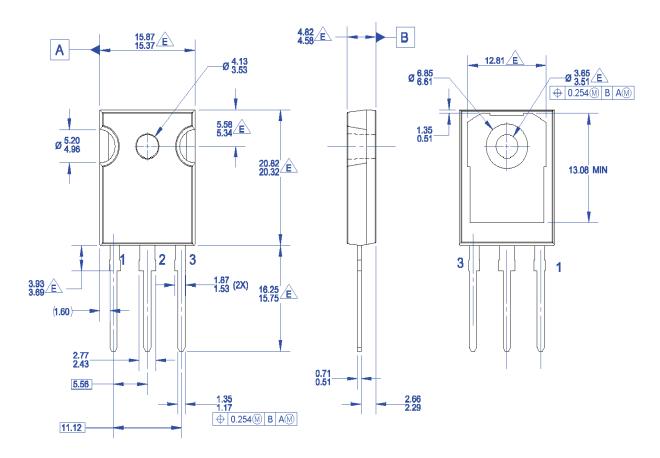


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **Mechanical Dimensions**



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